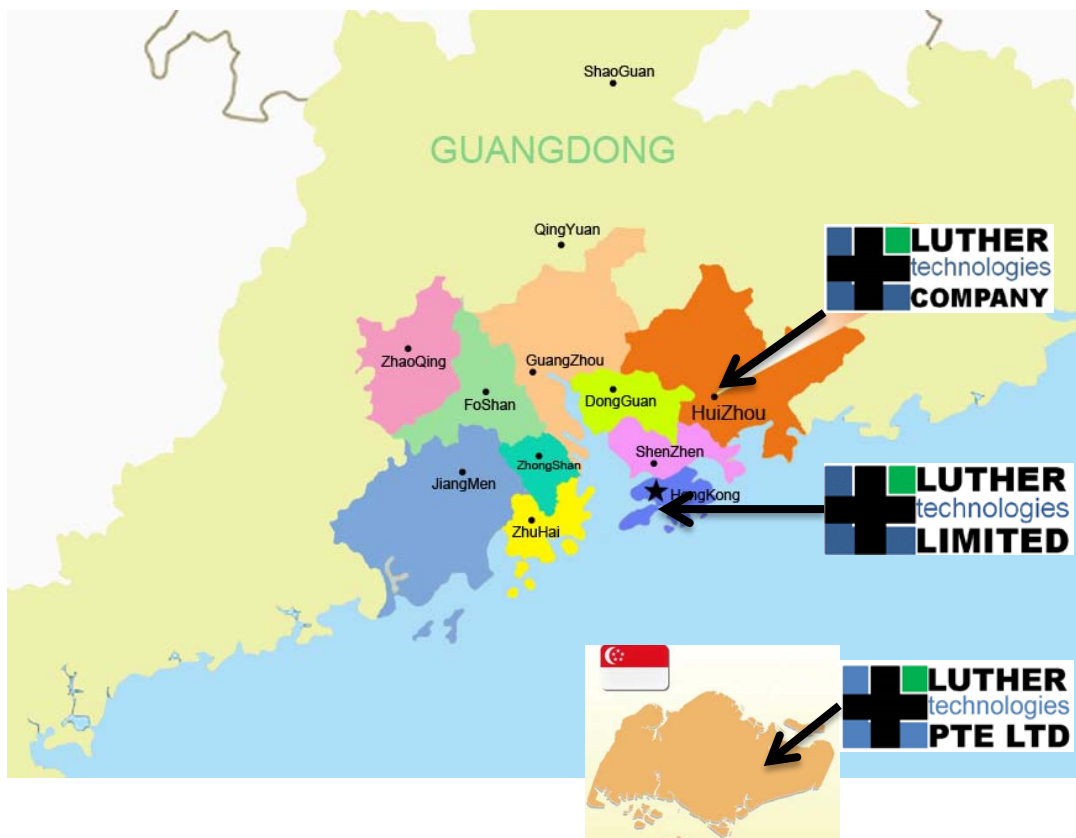


Company Profile:

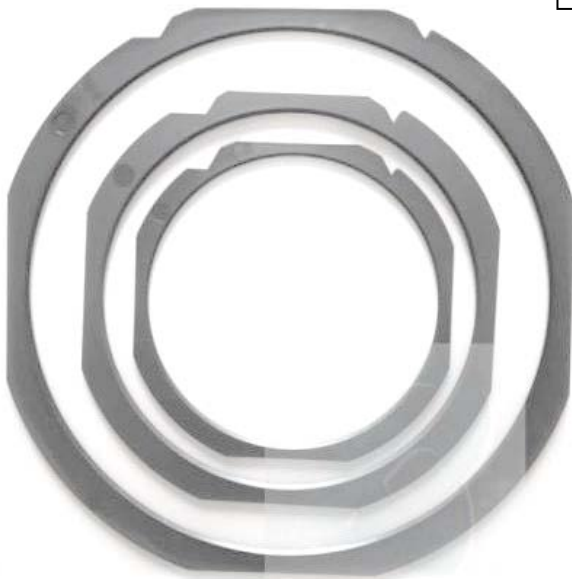
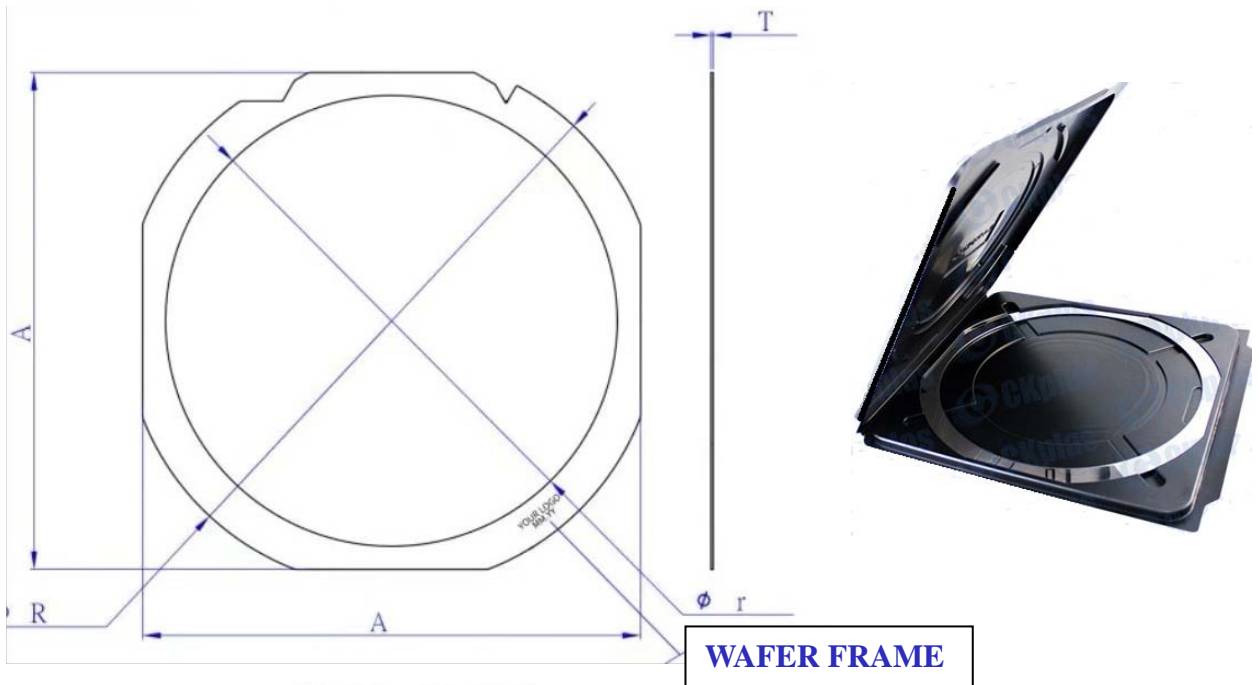
Luther is an international distribution and manufacturing company. Our headquarter is strategically sited in Hong Kong, while the company has affiliated offices in Singapore and China. We are professional supplier of industrial automation equipment and semiconductor/electronics industrial process consumables.

We listen to the voice of our customers, devote our core values of Integrity, Commitment and Mutual Respect to our customers. We are poised to meet the high demands of our customers through our strength in delivering the most Innovative Solution, Quality Products & Services at the most Competitive Price.



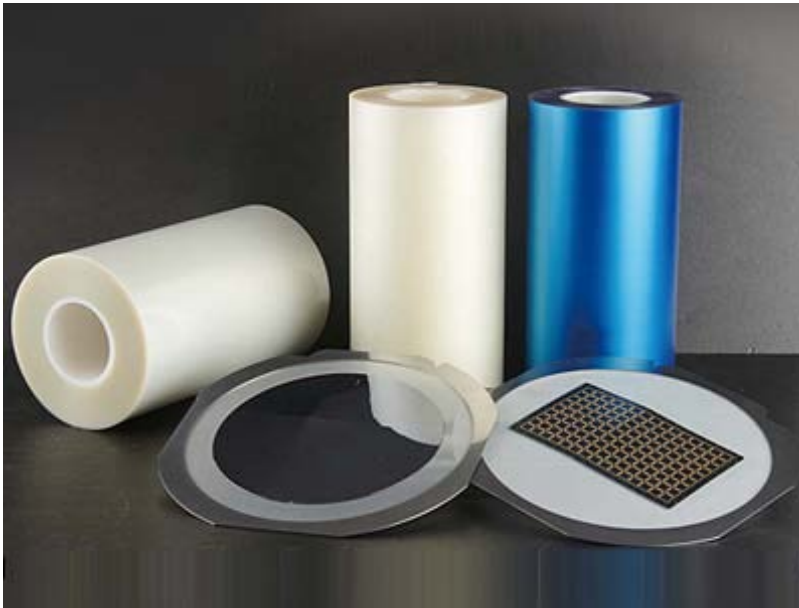
Wafer Frames

Model No#	A (mm)	r (mm)	T (mm)	Wafer Size (Inc)	Ind. Standard
LT-WF-D08	276	250	1.2	8"	Disco 8"
LT-WF-D12	380	350	1.5	12"	Disco 12"
LT-WF-K08	266.7	242.4	1.2	8"	K&S 8"
LT-WF-D06	212	194	1.2	6"	Disco6"



Material: SUS 420 Stainless Steel
 Or: SUS 304 Stainless Steel
 Hardness: HRC 48-52
 Finish: Mirror-like Polished
 Electroless Nickel-plated
 Type: For 6" , 8" and 12" wafers

Wafer Dicing Tapes



UV CURABLE DICING TAPES

Base Material : PO film, PET film, PVC film
Adhesion(gf/25mm) : 200~2500 (Before UV), 10~25 (After UV)
Thickness : 90 ~ 170 μm
Elongation (%) : 600



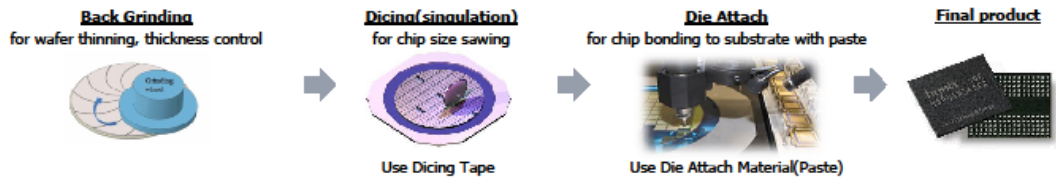
NON UV DICING TAPES

Base Material : PVC film
Adhesion(gf/25mm) Peeling Strength : 10 ~ 180
Thickness : 80 μm
Elongation (%) : 300

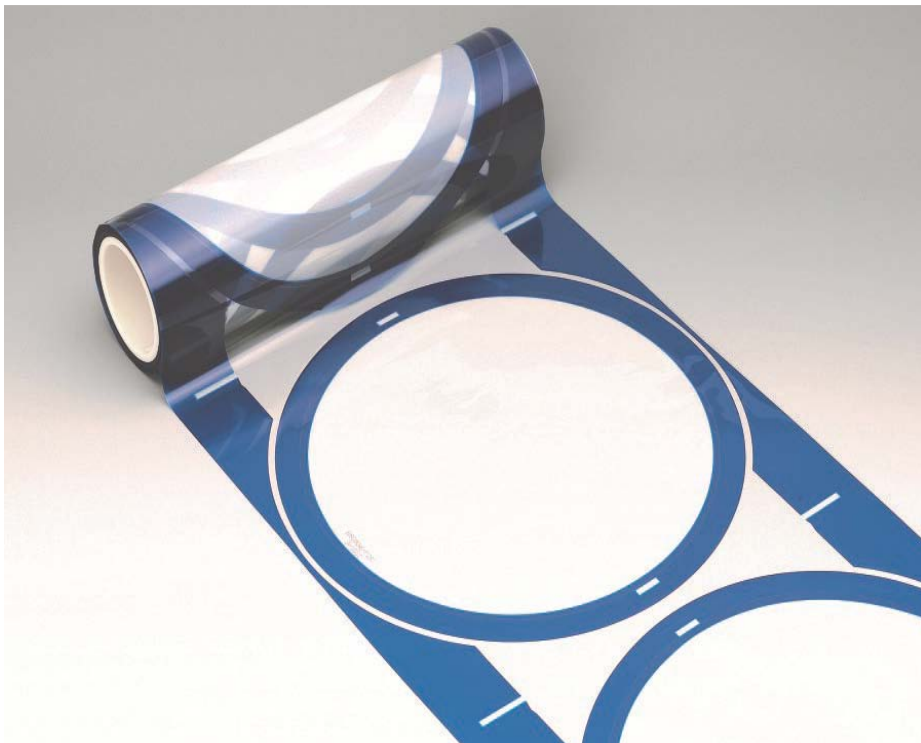
DAF Process

Through DAF application, semiconductor packaging companies can get 1-step process reducing, It benefits and overcomes the weakness of silver paste attach process.

Conventional(Paste) Process



DAF Process



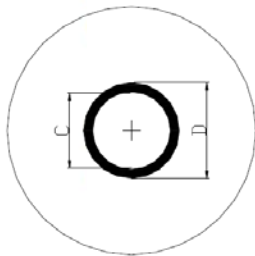
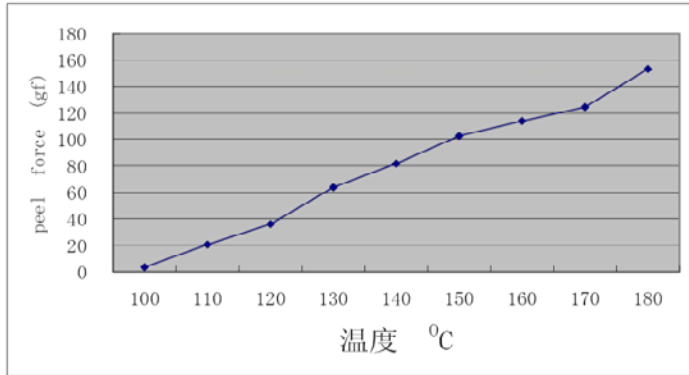
Wire Bonder EFO Wands

EFO Electronic Flame-Off Wands:

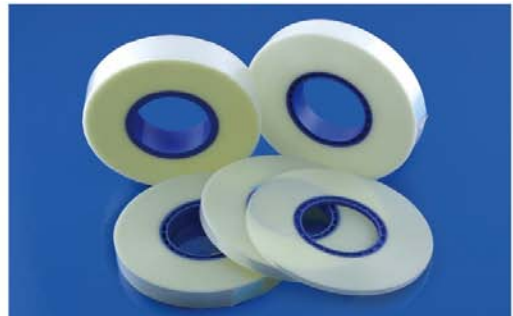
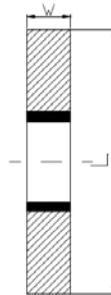
ASM	ASM	ESEC	KAIJO	SHK
				
Fits on Bonder ASM AB309	Fits on Bonder ASM AB339 ASM Eagle 60	Fits on Bonder ESEC 3006 ESEC 3008 ESEC 3018 ESEC 3088	Fits on Bonder KAIJO FB- 131	Fits on Bonder Shinkawa UTC-3000
K&S	K&S	K&S	SHK	SHK
				
Fits on Bonder K&S 8020 K&S 8098	Fits on Bonder K&S 8020 K&S 8098	Fits on Bonder K&S 8028 K&S Maxum K&S Nutek K&S Elite	Fits on Bonder Shinkawa UTC-200	Fits on Bonder Shinkawa UTC-1000

Provide consistent free air ball formation & ball shape uniformity. Consistent ball size control

Cover Tapes



C=76.2 ± 0.5mm
D=92.2 ± 1.3mm
L=164.0 ± 1.5mm



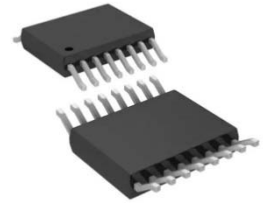
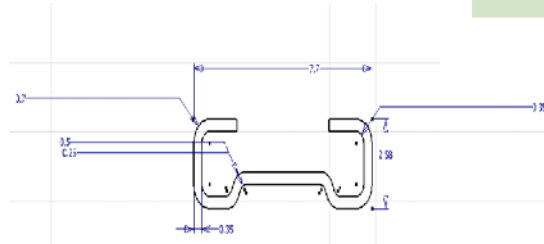
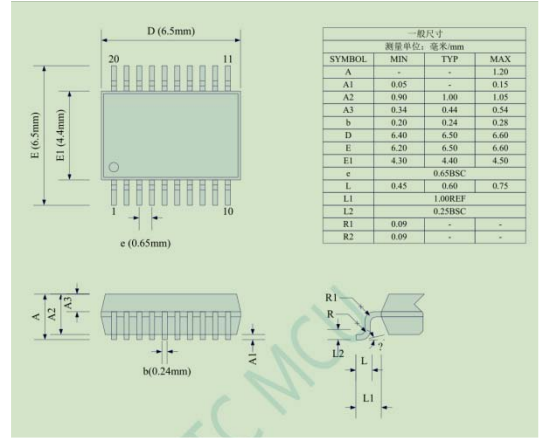
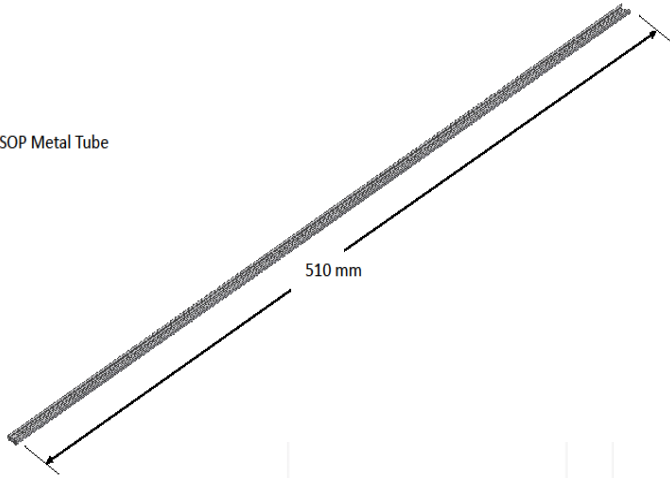
Carrier Tape Width / 载带宽度	8	12	16	24	32	44	56
Cover Tape Width / 盖带宽度(mm)	5.3	9.3	13.3	21.3	25.5	37.5	49.5
Roll / Case (Roll) / 卷/箱	25	15	11	7	6	4	3
Roll / Case (KG) / 卷/重量(KG)	0.12	0.15	0.22	0.35	0.42	0.62	0.85
CTN / Case (KG) / 箱/重量(KG)	3.75	3.13	3.28	3.33	3.40	3.36	3.43
Common Width Difference / 公差(mm)	± 0.1						
Thickness (mm) / 厚度	0.060 ± 0.005						
Length (m) / 长度	300, 480, 600, 1500, 3000 + 3, - 3						
Core Means / 轴芯	3 inch (76.2mm)						

Material Specifications	TYPICAL VALUE (实测值)	TEST METHOD (方法)
ELECTRICAL PROPERTIES (电性)		
Static Decay(+ 5kv~-5kv) 静电消散时间	< 0.1 Sec.	FTMS 101C 4046.1
Surface Resistivity 表面阻抗 (single surface 12%RH, 230C)	< 10 ¹² Ω/ CM SQ.	ASTM - D257
PHYSICAL PROPERTIES (物性)		
Thickness : Total (总厚度)	60μ ± 5μ	
Substrate (基材)	15μ ± 5%	
Polyethylene (缓冲材)	15μ ± 5%	
Adhesive (粘着材)	30μ ± 5%	
Tensile strength (MD) (引张强度)	> 4 kg / 15mm	JIS Z-1707
Elongation (MD) (延伸率)	> 70 %	JIS Z-1707
CHEMICAL PROPERTIES (化性)	ESD contains no Amines , N-Octanoic Acid	

Metal Tubes

Material: Stainless Steel SS304

TSSOP Metal Tube



Model No#	L (mm)	W (mm)	H (mm)
LT-MT-TSSOP	510	7.0	2.4
LT-MT-MSOP	400	6.5	2.0
LT-MT-SSOP	400	6.5	2.0

Test Contact Fingers and Sockets



Package	SOP	TSSOP	DFN/QFN	TO-XXX
CONTACT RESISTANCE	> 100mOhms	>80mOhms	>38mOhms	>100mOhms
MAX CURRENT	4.4A	3.1A	2.0A	3.0A
MAX CURRENT PULSE	20A @10%	20A @10%	3.9A @10%	15A@10%
LIFE CYCLES	> 2000K	> 2000K	> 300K	> 2000K



Package	SOP	TSSOP	DFN/QFN	TO-XXX
CONTACT RESISTANCE	> 100mOhms	>80mOhms	>38mOhms	>100mOhms
MAX CURRENT	4.4A	3.1A	2.0A	3.0A
MAX CURRENT PULSE	20A @10%	20A @10%	3.9A @10%	15A@10%
LIFE CYCLES	> 2000K	> 2000K	> 300K	> 2000K

